









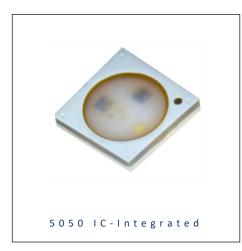
PRODUCT DATASHEET



- ► SMD with Touch IC
- ► 5050 IC 1.0t
- ► W/R/G/B + Touch Sensor

NOM61S47ICT









Release Date: 18 September 2022 Version: A1.1

FEATURES:

- Package: Top View Package with Touch Detection and WRGB Integrated IC Control
- Forward Current: 12/12/12/12mA* Forward Voltage (typ.): +3.3~+5.5V
- Luminous Intensity (typ.): 580/320/700/150mcd
- Colour: Sky White/Red/Green/Blue
- CCT/Wavelength: 9900K/622/525/468nm
- Viewing angle: 120°
- **Materials:**
 - Resin: Silicone (White Diffused)
 - L/F Finish: Ag Plated
- Operating Temperature: -25~+85°C
- Storage Temperature: -30~+100°C
- Pixel: 256 step gray-scale output to allow 4294M colour display
- Touch Sensor Type: Capacitive Sensing
- Soldering methods: IR Reflow soldering
- Preconditioning: acc. to JEDEC Level 3
- Packing: 12mm tape with max.1000pcs/reel, ø180mm (7")

APPLICATIONS:

- Telecommunication
- Indicator
- Home Appliance
- **Decoration Lighting**
- Full Colour LED Strip
- **Gaming Device**
- **Guardrail Tube**
- **Button Keys**

^{*} in order of White/Red/Green/Blue



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V_{DD}	3.3 ~ 5.5	V
Operating Temperature	Topr	-25~+85	°C
Storage Temperature	T _{STG}	-30~+100	°C

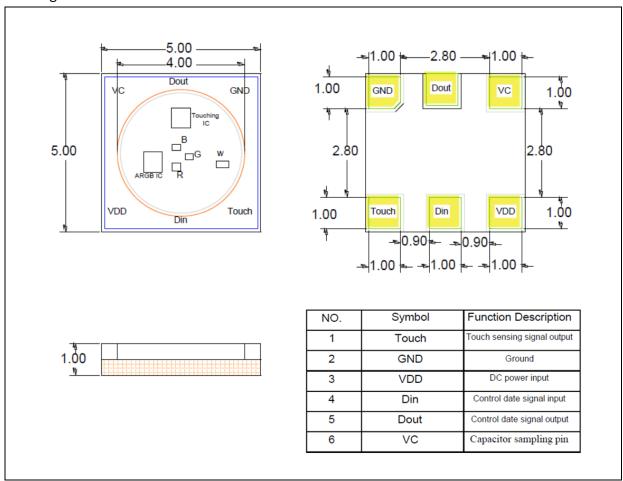
Electrical & Optical Characteristics (Ta=25°C, V_{DD}=5V)

Р	arameter		Symbol		Values	Unit	Test		
•	arameter		3,111331	Min.	Тур.	Max.	Sinc	Condition	
	Supply Vol	tage	V_{DD}	3.3	5.0	5.5	V		
	Standby Cu	ırrent	I _{OPL}		10.5		μΑ	V _{DD} =5V No Load	
Touch Sensing IC	High Level Voltage	Input	V _{IH}	2/3			V_{DD}	V_{DD}	
	Low Level Voltage	nput	V _{IL}			1/3	V_{DD}	V_{DD}	
	Output Res Time	sponse	T _R		48		ms	V _{DD} =5V	
	Supply Vol	tage	V_{DD}	3.3	5.0	5.5	V		
Addressab	Each R/G/E Current	3	loL		12		mA	V _{DD} =5V	
le RGB IC	Input High Voltage		V _{IH}	2.7		V_{DD}	V		
	Input Low	Voltage	VIL	0		1	V		
		W			580				
Luminaus Im	t ancity	R	lv		320		mcd	V _{DD} =5V	
Luminous In	itensity	G	IV		700		ilica	VDD-3V	
		В			150				
Colour Tem	perature	W	ССТ		9900		K	V _{DD} =5V	
		R			622				
Dominant W	/avelength	G	λ_{D}		525		nm	V _{DD} =5V	
		В			468				
Viewing Ang	gle		2θ _{1/2}		120		deg	V _{DD} =5V	



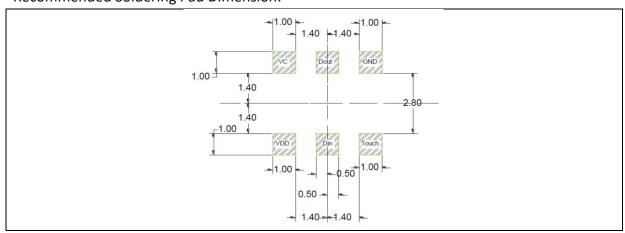
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

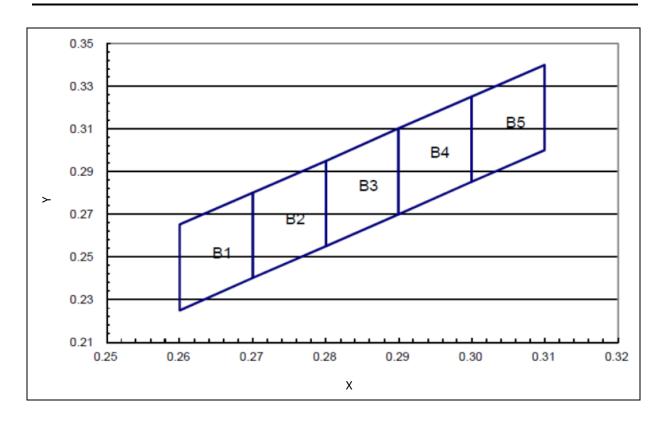
Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



CIE CHROMATICITY DIAGRAM:

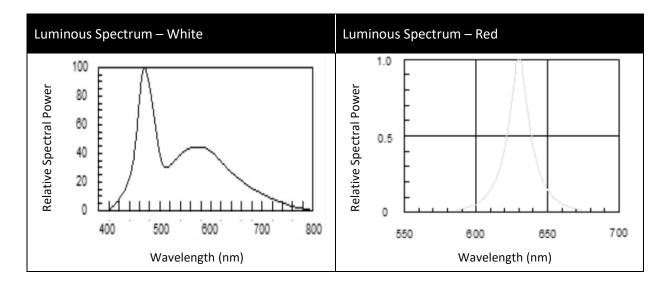


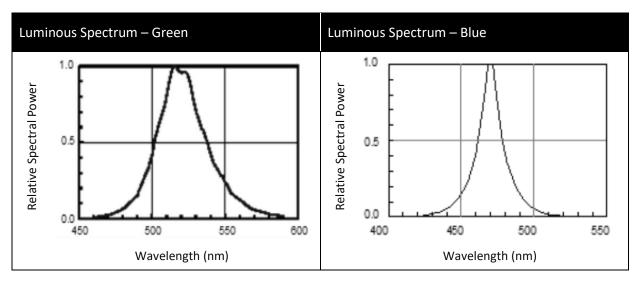
Chromaticity Coordinates Classifications:

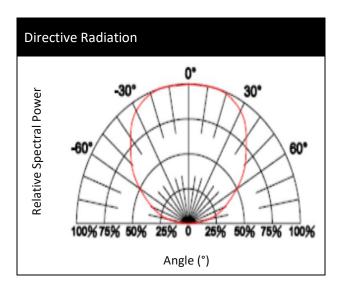
	1	1	2	2	3	3	2	4		
	Х	Υ	Х	Υ	Х	Υ	Х	Υ		
B1	0.2600	0.2650	0.2600	0.2250	0.2700	0.2400	0.2700	0.2800		
B2	0.2700	0.2800	0.2700	0.2400	0.2800	0.2550	0.2800	0.2950		
В3	0.2800	0.2950	0.2800	0.2550	0.2900	0.2700	0.2900	0.3100		
B4	0.2900	0.3100	0.2900	0.2700	0.3000	0.2850	0.3000	0.3250		
B5	0.3000	0.3250	0.3000	0.2850	0.3100	0.3000	0.3100	0.3400		



ELECTRO-OPTICAL CHARACTERISTICS:









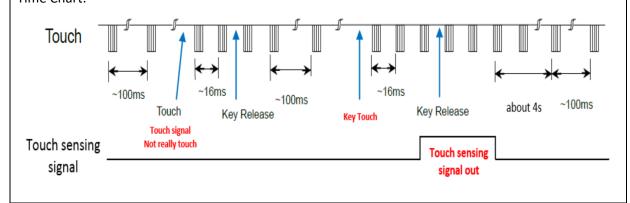
Function Description:

1. Touch Sensing Function:

Features:

- At low power mode typical 10.5uA@5V.
- Sensitivity can adjust by the capacitance outside.
- · Auto calibration for life.
- Stable touching detection with isolation object cover the component.

Time Chart:

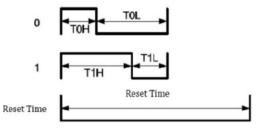


2. Addressable RGB Function:

Features:

- Support control circuit to be integrated with RGB chips into a single package.
- Support signal reshaping to pass control waveforms to next adjacent driver.
- 256-step gray-scale output to allow 4294M colour display.
- Constant current PWM control.

Timing Wave Form:

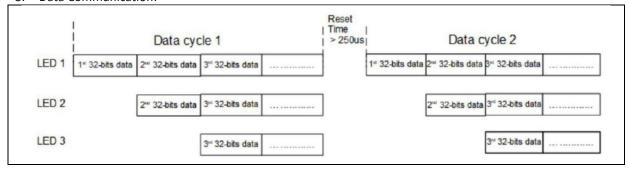


Item	Description	min	Typical	Allowance	unit
тон	0 code, High-level time		0.3	±0.15	us
TOL	0 code, Low-level time		0.9	±0.15	us
T1H	1 code, High-level time		0.9	±0.15	us
T1L	1 code, Low-level time		0.3	±0.15	us
Trst	Reset code,Low-level time	250			us

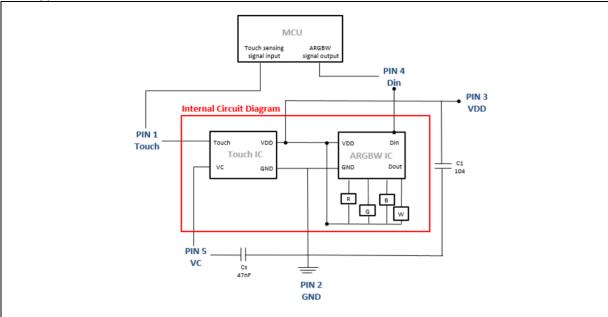


Single data in 32 bits for RGB:																																	
	MS	В																												LS	В	_	
																											_						
		8	R 5		R 3	R 2	R 1	R 0	G 7	G 6	G 5	G 4	G 3	G 2	G 1	G 0	B 7	B 6	B 5	B 4	B 3	B 2	B 1	B 0	W 7	W 6	W 5	W 4	W 3	W 2	W 1	w	

3. Data Communication:



4. Application Circuit:



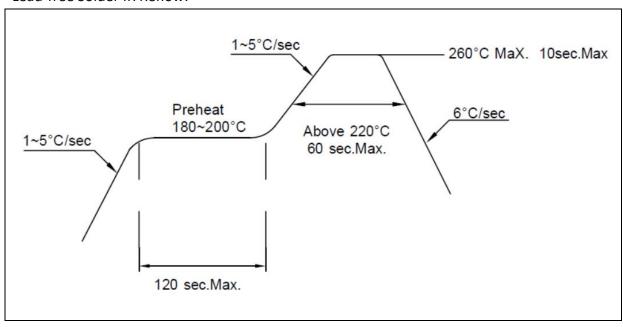
Application Note:

- 1. Initial Pin 1 (Touch) output is 0 (Low level) as power on. When touching sensor detect a touch, Pin 1 (Touch) switch to 1 (High level). When the touching sensing is removed. It will switch Pin 1 (Touch) from 1 (High level) to 0 (Low level).
- 2. When Pin5 (VC) is Adding the Cs (47nF) to VSS, the sensitivity is most sensitive. When reduce the values of Cs. It will reduce sensitivity in the useful range. ($1nF \le Cs \le 47nF$).
- 3. The material of panel covering on the PCB cannot include the metal or the electric element. The paints on the surfaces are the same. The cover's thickness design rule is under 2mm.
- 4. The power supply must be stable. If the supply voltage drift or shift quickly, maybe causing sensitivity anomalies or false detections.
- 5. The sensitivity adjustment capacitors (Cs) must use smaller temperature coefficient and more stable capacitors. Such are X7R, NPO for example. So for touch application, recommend to use NPO capacitor, for reducing that the temperature varies to affect sensitivity.



RECOMMENDED SOLDERING PROFILE:

Lead-free Solder IR Reflow:



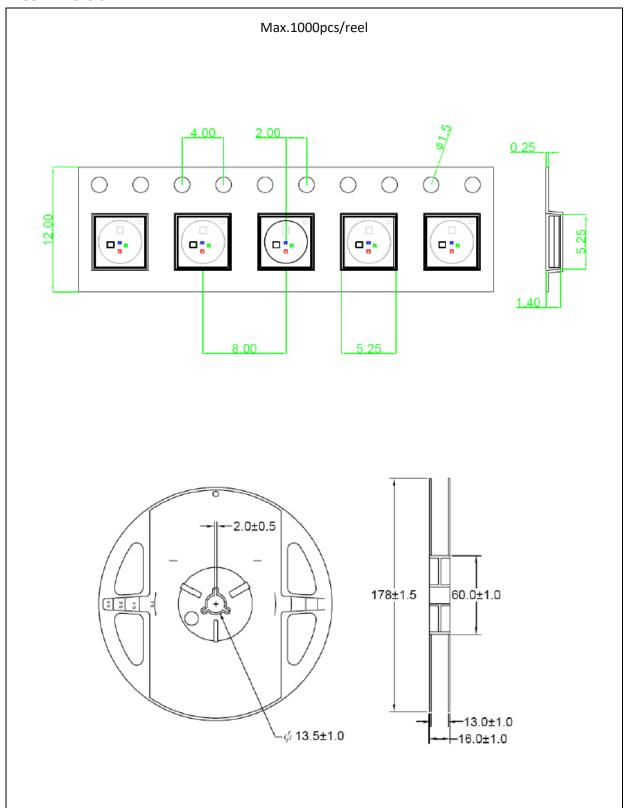
Note:

- 1. We recommend the reflow temperature 240°C (±5°C). The maximum soldering temperature should be limited to 260°C.
- 2. Maxima reflow soldering: 2 times.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within 72 hours. Otherwise, they should be kept in a damp-proof box with descanting agent stored at R.H.<10% and apply baking before use.

Over-Current Proof:

Must apply resistors for protection otherwise slight voltage shift will cause big current change and burnout will happen.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Recommended Route:

Parallel connected multi-strip control.

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	05/08/2021	Datasheet set-up.
A1.1	18/09/2022	Add packing drawing.